



Himax Announces 5.5MP UltraSenseIR™ BSI Image Sensor with 2X Higher Near Infrared Sensitivity for Computer Vision and NIR Imaging Camera

TAINAN, Taiwan – December 27, 2016 – Himax Imaging, Inc., a subsidiary of Himax Technologies, Inc. (Nasdaq: HIMX) (“Himax” or the “Company”), a leading global supplier and fabless manufacturer of display drivers and other semiconductor products, today announced the HM5530 UltraSenseIR™ product, a low power and low noise 5.5 Megapixel Back Side Illuminated (“BSI”) CMOS Image Sensor (“CIS”) with more than 40% quantum efficiency in the Near Infrared (“NIR”) spectrum enabling the next generation of embedded computer vision applications such as 3D camera, autonomous navigation, event and pattern recognition and human-machine interaction.

“Computer and machine vision devices operate unnoticed to human perception by using Near Infrared light sources and sensors because NIR is not visible to the human eye. Silicon based image sensor, which is the dominant technology for visual imaging applications due to advantages in cost, power and scalability, is not sensitive to the Near Infrared spectrum and needs to be compensated by using relatively large pixel sizes to confine the resolution of the sensor that can fit in an embedded device,” said Amit Mittra, CTO of Himax Imaging. “With our breakthrough UltraSenseIR™ technology, Himax combines the advantages of our highly integrated, low power and low noise BSI sensor technologies with NIR and visible sensitivity in a very small 2.0-micron pixel size to enable high resolution computer vision and NIR imaging applications.”

The HM5530 consumes less than 140mW at 5.5 Megapixel operating at 30 frames per second over industry compliant MIPI CSI2 interface. The sensor timing supports frame synchronization to an external LED or Laser Diode light source, and can be programmed using a standard two wire serial interface. With engineering samples ready, Himax Imaging Inc. is collaborating with platform providers to provide integrated solution for computer vision.

About Himax Technologies, Inc.

Himax Technologies, Inc. (NASDAQ:HIMX) is a fabless semiconductor solution provider dedicated to display imaging processing technologies. Himax is a worldwide market leader in display driver ICs and timing controllers used in TVs, laptops, monitors, mobile phones, tablets, digital cameras, car navigation, virtual reality (VR) devices and many other consumer electronics devices. Additionally, Himax designs and provides controllers for touch sensor displays, in-cell Touch and Display Driver Integration (TDDI) single-chip solutions, LED driver ICs, power management ICs, scaler products for monitors and projectors, tailor-made video processing IC solutions, silicon IPs and LCOS micro-displays for augmented reality (AR) devices and heads-up displays (HUD) for automotive. The Company also offers digital camera solutions, including CMOS image sensors and wafer level optics, which are used in a wide variety of applications such as mobile phone, tablet, laptop, TV, PC camera, automobile, security, medical devices and Internet of Things. Founded in 2001 and headquartered in Tainan, Taiwan, Himax currently employs around 2,100 people from three Taiwan-based offices in Tainan, Hsinchu and Taipei and country offices in China, Korea, Japan and the US. Himax has 2,911 patents granted and 458 patents pending approval worldwide as of September 30th, 2016. Himax has retained its position as the leading display imaging processing semiconductor solution provider to consumer electronics brands worldwide.

<http://www.himax.com.tw>

About Himax Imaging (A subsidiary of Himax Technologies)

Himax Imaging is a fabless semiconductor company that develops CMOS Image Sensors (CIS), system-on-chip (SOC) and wafer level camera solutions for next generation camera, video communication and sensing applications. As a relative newcomer in the CIS industry, Himax Imaging has quickly developed a broad portfolio of products and technologies that have been adopted by leading mobile computing and communication device manufacturers. For more information, please visit: <http://himaximaging.com/>.

Forward Looking Statements

Factors that could cause actual events or results to differ materially include, but not limited to, general business and economic conditions and the state of the semiconductor industry; market acceptance and competitiveness of the driver and non-driver products developed by the Company; demand for end-use applications products; reliance on a small group of principal customers; the uncertainty of continued success in technological innovations; our ability to develop and protect our intellectual property; pricing pressures including declines in average selling prices; changes in customer order patterns; changes in estimated full-year effective tax rate; shortages in supply of key components; changes in environmental laws and regulations; exchange rate fluctuations; regulatory approvals for further investments in our subsidiaries; our ability to collect accounts receivable and manage inventory and other risks described from time to time in the Company's SEC filings, including those risks identified in the section entitled "Risk Factors" in its Form 20-F for the year ended December 31, 2015 filed with the SEC, as may be amended.

Company Contacts:

Jackie Chang, CFO

Himax Technologies, Inc.

Tel: +886-2-2370-3999 Ext.22300

Or

US Tel: +1-949-585-9838 Ext.252

Fax: +886-2-2314-0877

Email: jackie_chang@himax.com.tw

www.himax.com.tw

Penny Lin, Investor Relations

Himax Technologies, Inc.

Tel: +886-2-2370-3999 Ext.22320

Fax: +886-2-2314-0877

Email: penny_lin@himax.com.tw

www.himax.com.tw

Investor Relations - US Representative

Greg Falesnik, Managing Director

MZ North America

Tel: +1-212-301-7130

Email: greg.falesnik@mzgroup.us

www.mzgroup.us